

Absolute Maximum Ratings (@T_A = +25 °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-45	V
Collector-Emitter Voltage (Forward Blocking)	V _{CEO}	-40	V
Emitter-collector voltage (Reverse Blocking)	V _{ECO}	-3	V
Emitter-Base Voltage	V _{EBO}	-7	V
Continuous Collector Current (Note 5)	I _C	-1.5	A
Base Current	I _B	-500	mA
Peak Pulse Current	I _{CM}	-5	A

Thermal Characteristics (@T_A = +25 °C, unless otherwise specified.)

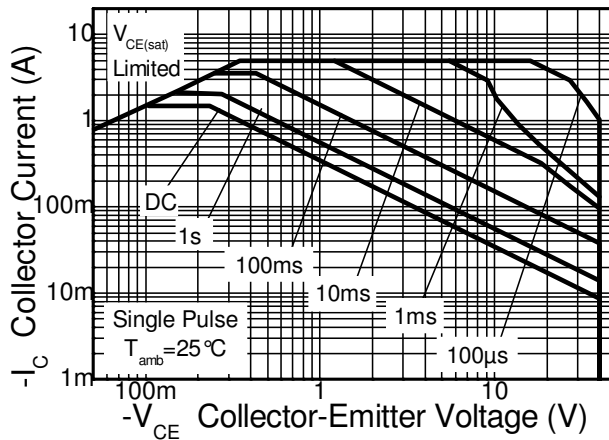
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	310	mW
(Note 6)		350	
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	403	°C/W
(Note 6)		357	
Thermal Resistance, Junction to Leads (Note 7)	R _{θJL}	350	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

ESD Ratings (Note 8)

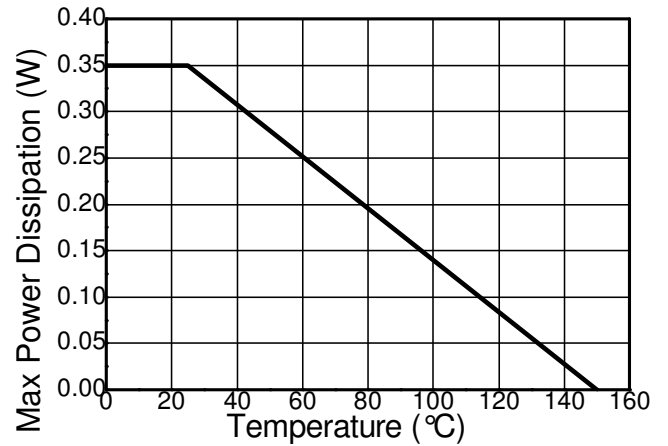
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
- For a device mounted on minimum recommended pad layout 1oz copper that is on a single-sided FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
 - Same as Note 5, except the device is mounted on 15 mm x 15mm 1oz copper.
 - Thermal resistance from junction to solder-point (at the end of the leads).
 - Refer to JEDEC specification JESD22-A114 and JESD22-A115.

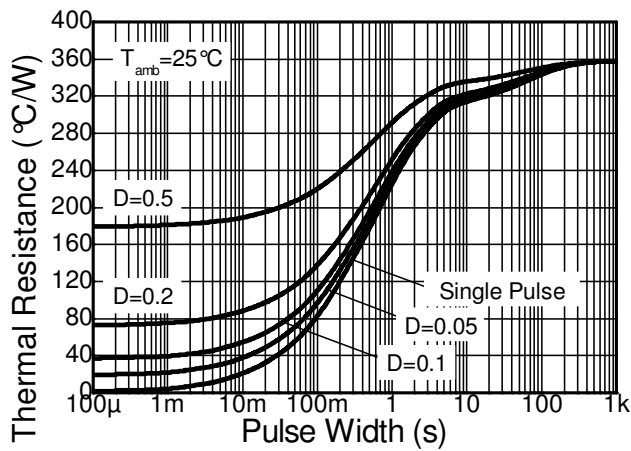
Thermal Characteristics and Derating Information



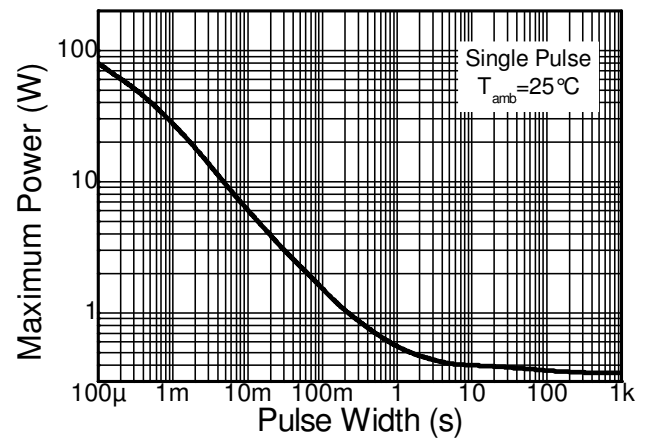
Safe Operating Area



Derating Curve



Transient Thermal Impedance



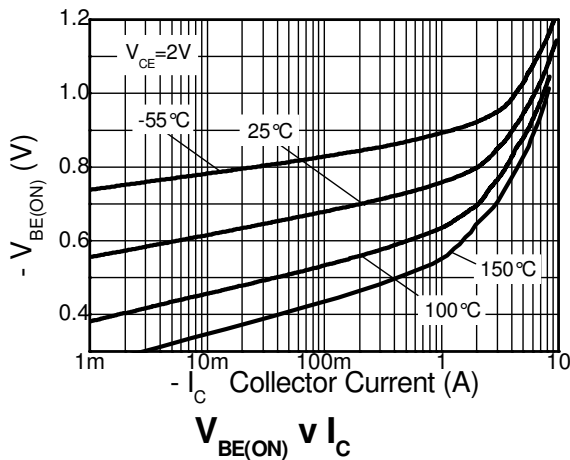
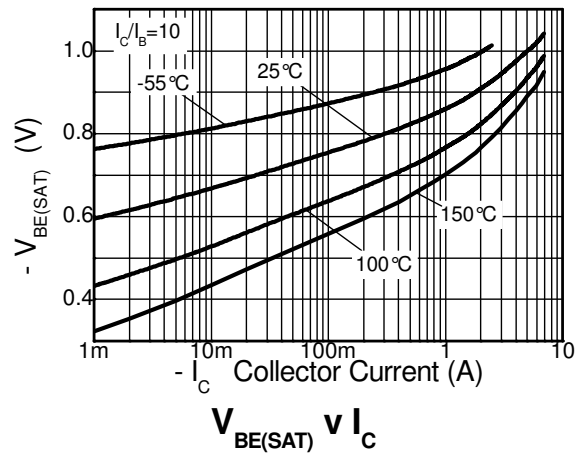
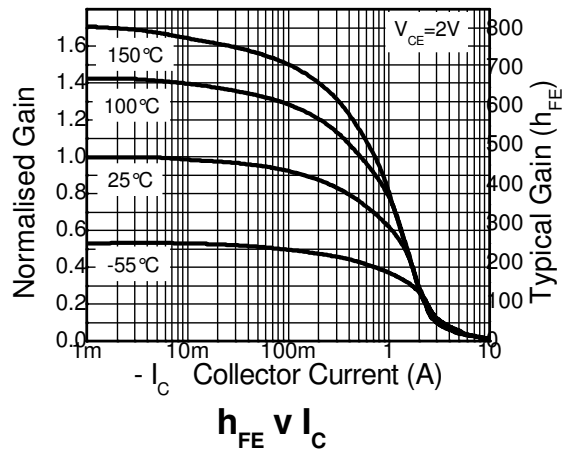
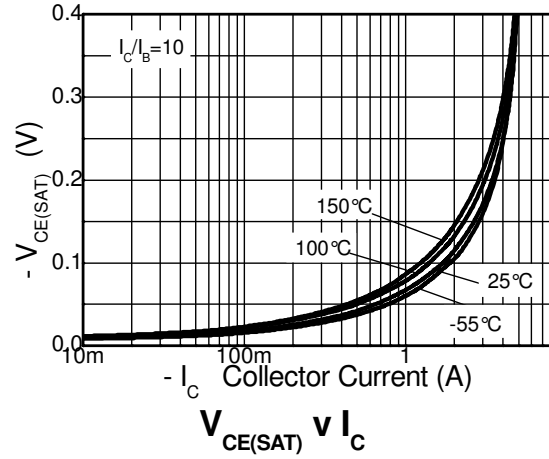
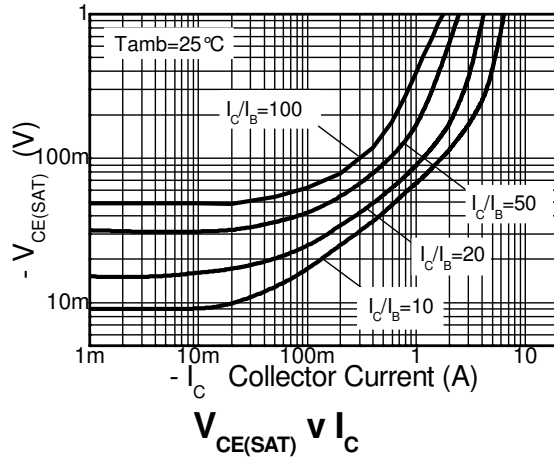
Pulse Power Dissipation

Electrical Characteristics (@T_A = +25 °C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	-45	-75	-	V	I _C = -100μA
Collector-Emitter Breakdown Voltage (Note 9)	BV _{CEO}	-40	-65	-	V	I _C = -10mA
Emitter-Base Breakdown Voltage	BV _{EBO}	-7	-8.2	-	V	I _E = -100μA
Emitter-Base Breakdown Voltage	BV _{ECO}	-3	-8.7	-	V	I _E = -100μA
Collector-Base Cutoff Current	I _{CBO}	-	< -1	-50	nA	V _{CB} = -36V
		-	-	-20	μA	V _{CB} = -36V, T _{amb} = +100 °C
Emitter-Base Cutoff Current	I _{EBO}	-	< -1	-50	nA	V _{EB} = -5.6V
Static Forward Current Transfer Ratio (Note 9)	h _{FE}	300	450	900	-	I _C = -10mA, V _{CE} = -2V
		120	200	-		I _C = -1.5A, V _{CE} = -2V
		15	40	-		I _C = -3A, V _{CE} = -2V
Collector-Emitter Saturation Voltage (Note 9)	V _{CE(sat)}	-	-75	-95	mV	I _C = -0.5A, I _B = -20mA
		-	-200	-290		I _C = -1A, I _B = -20mA
		-	-95	-115		I _C = -1A, I _B = -100mA
		-	-160	-190		I _C = -1.5A, I _B = -75mA
		-	-245	-300		I _C = -3A, I _B = -300mA
Base-Emitter Saturation Voltage (Note 9)	V _{BE(sat)}	-	-915	-1000	mV	I _C = -1.5A, I _B = -75mA
Base-Emitter Saturation Voltage (Note 9)	V _{BE(on)}	-	-825	-900	mV	I _C = -1.5A, V _{CE} = -2V
Output Capacitance	C _{obo}	-	17.4	25	pF	V _{CB} = -10V, f = 1MHz
Transition Frequency	f _T	-	270	-	MHz	V _{CE} = -10V, I _C = -50mA, f = 50MHz
Delay Time	t _(d)	-	34	-	ns	V _{CC} = -15V, I _C = -750mA, I _{B1} = -I _{B2} = -15mA
Rise Time	t _(r)	-	41	-	ns	
Storage Time	t _(s)	-	266	-	ns	
Fall Time	t _(f)	-	53	-	ns	

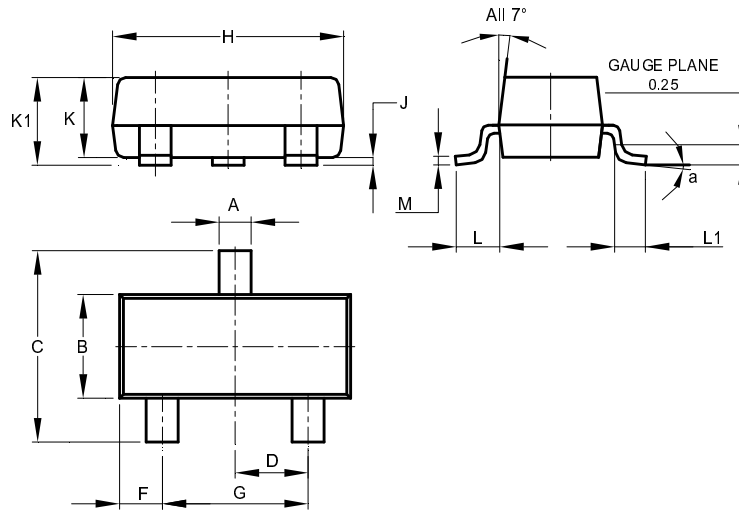
Notes: 9. Measured under pulsed conditions. Pulse width ≤ 300 μs. Duty cycle ≤ 2%.

Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)



Package Outline Dimensions

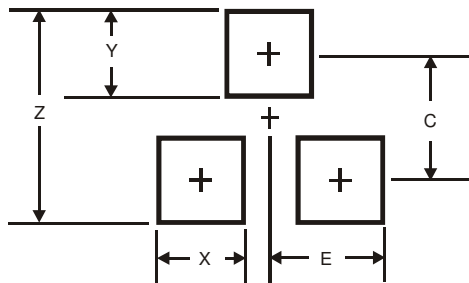
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.890	1.00	0.975
K1	0.903	1.10	1.025
L	0.45	0.61	0.55
L1	0.25	0.55	0.40
M	0.085	0.150	0.110
a	8°		
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

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